

L Number	Hits	Search Text	DB	Time stamp
-	334	29/829.ccls.	USPAT; US-PGPUB	2002/12/10 15:46
-	302	29/842.ccls.	USPAT; US-PGPUB	2002/12/10 15:46
-	763	29/874.ccls.	USPAT; US-PGPUB	2002/12/10 15:46
-	387	29/884.ccls.	USPAT; US-PGPUB	2002/12/11 14:06
-	69	29/884.ccls. and @py<2000 and (taper\$2 cone conical)	USPAT; US-PGPUB	2002/12/11 14:04
-	85	29/874.ccls. and @py<2000 and (taper\$2 cone conical)	USPAT; US-PGPUB	2002/12/11 14:37
-	76	(29/874.ccls. and @py<2000 and (taper\$2 cone conical)) not 29/884.ccls.	USPAT; US-PGPUB	2002/12/11 14:07
-	687	29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2 cone conical)) not 29/884.ccls.)	USPAT; US-PGPUB	2002/12/11 14:37
-	609	(29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2 cone conical)) not 29/884.ccls.)) and @py<2000	USPAT; US-PGPUB	2002/12/11 14:37
-	131	((29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2 cone conical)) not 29/884.ccls.)) and @py<2000) and method.ti.	USPAT; US-PGPUB	2002/12/11 14:38
-	52	((((29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2 cone conical)) not 29/884.ccls.)) and @py<2000) and method.ti.) and (printed adj circuit adj board pc adj board substrate wafer laminat\$2)	USPAT; US-PGPUB	2002/12/11 15:12
-	1077	216/41, 44.ccls. and @py<2000	USPAT; US-PGPUB	2002/12/11 15:11
-	808	(216/41, 44.ccls. and @py<2000) and (printed adj circuit adj board pc adj board substrate wafer laminat\$2)	USPAT; US-PGPUB	2002/12/12 15:50
-	79	((216/41, 44.ccls. and @py<2000) and (printed adj circuit adj board pc adj board substrate wafer laminat\$2)) and corros\$3	USPAT; US-PGPUB	2002/12/11 15:14
-	71	((216/41, 44.ccls. and @py<2000) and (printed adj circuit adj board pc adj board substrate wafer laminat\$2)) and method.ti. and (corros\$3 salt salin\$3)	USPAT; US-PGPUB	2002/12/12 13:30
-	1	6171164.pn.	USPAT; US-PGPUB	2002/12/11 15:41
-	1	5391259.pn.	USPAT; US-PGPUB	2002/12/12 13:34
-	1	5302238.pn.	USPAT; US-PGPUB	2002/12/12 14:02
-	385	257/775.ccls.	USPAT; US-PGPUB	2002/12/12 14:03
-	237	257/775.ccls. and @py<2000	USPAT; US-PGPUB	2002/12/12 14:24
-	43	(257/775.ccls. and @py<2000) and method.ti.	USPAT; US-PGPUB	2002/12/12 14:24
-	264	438/754.ccls.	USPAT; US-PGPUB	2002/12/12 14:49
-	62	438/754.ccls. and @py<2000 and method.ti.	USPAT; US-PGPUB	2002/12/12 14:50
-	96	438/673.ccls.	USPAT; US-PGPUB	2002/12/12 15:44
-	31	438/673.ccls. and @py<2000 and method.ti.	USPAT; US-PGPUB	2002/12/12 15:47
-	567	438/669.ccls.	USPAT; US-PGPUB	2002/12/12 15:44
-	201	438/669.ccls. and @py<2000 and method.ti.	USPAT; US-PGPUB	2002/12/12 15:49
-	185	(438/669.ccls. and @py<2000 and method.ti.) and (printed adj circuit adj board pc adj board substrate wafer laminat\$2) not ((257/775.ccls. and @py<2000) and method.ti.) not (438/754.ccls. and @py<2000 and method.ti.) not (438/673.ccls. and @py<2000 and method.ti.)	USPAT; US-PGPUB	2002/12/12 16:10
-	789020	printed adj circuit adj board pc adj board substrate wafer laminat\$2) (plated plating) (rhodium palladium gold	USPAT; US-PGPUB	2002/12/12 16:26

-	909334	(printed adj circuit adj board pc adj board substrate wafer laminat\$2) (plated plating) (rhodium palladium gold) and (etch remov\$2) anisotropic (taper\$3 cone conical)	USPAT; US-PGPUB	2002/12/12 16:22
-	16041	(printed adj circuit adj board pc adj board substrate wafer) and ((plated plating) same (rhodium palladium gold))	USPAT; US-PGPUB	2002/12/12 16:26
-	772	((printed adj circuit adj board pc adj board substrate wafer) and ((plated plating) same (rhodium palladium gold))) and (etch remov\$2) and anisotropic and (taper\$3 cone conical point\$2 sharp)	USPAT; US-PGPUB	2002/12/12 16:28
-	159	((((printed adj circuit adj board pc adj board substrate wafer) and ((plated plating) same (rhodium palladium gold))) and (etch remov\$2) and anisotropic and (taper\$3 cone conical point\$2 sharp)) and (contact bump\$2 electrode) and method.ti. and @py<2000	USPAT; US-PGPUB	2002/12/12 16:32